



Material declaration form

General information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field
Supplier information			
Company name*	STMicroelectronics	Response date*	2025-03-20
Authorized representative*	Cyrille Boulloud	Representative title	APMS Material Declaration Champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance *	Legal declaration*	Standard
true		

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.



Product				
Manufacturing item number	Manufacturing item name	Version	Manufacturing site	Date
VB1740AAJX	A5JX*740RDA3	A	SC - AMKOR ATJ5 - JAPAN	2025-03-20
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	304	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
3	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Tin/Silver/Copper (SAC305)	Not Applicable	Copper Alloy	DM0112433 / 1F147707
Comment	OBGA74 8.9X10.3 9X10 0.8 0.5		

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true

QueryList : ELV directive : 2000/53/EC amended 2020/363_ March 2020	Response
1 - Product(s) meets EU ELV requirement without any exemptions	true

QueryList : California Prop65 list, dated 3rd January 2025	Response		
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen	false		
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen	true		
Substance	amount in product (mg)	Application	ppm in product
Nickel	1.200	Die	3950

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014	Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products	false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products	false

QueryList : REACH-21st January 2025	Response			
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	false			
CategoryLevel_Name	CategoryLevel_Threshold	Amount in product (mg)	Application	ppm in product
Diboron trioxide	1000 ppm	6.596863556	In Glass	21723
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Homogeneous Material above the limits per the definition within REACH	false			
CategoryLevel_Name	CategoryLevel_Threshold	Amount in homogeneous material (mg)	Application - homogeneous material	ppm in homogeneous material
Diboron trioxide	1000 ppm	6.596863556	Glass	79576
Diboron trioxide in glass : Allowed to use as dopant, in glass wafer and in glass fibers Restricted to 500 ppm in BE glues, in glass paste to 15% in weight Exemptions not applicable for new application				

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	true
QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true
QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	False
BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True
Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True
Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material composition declaration - note - Substance present with less 0.001mg will not be declared in this document						Manufacturing Item name	A5JX740RDA3		303.6800		8000000.0	1000000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	17.780	mg	supplier	die	Silicon(Si)	7440-21-3		16.441	mg	924691	54139
				supplier	metallisation	Copper(Cu)	7440-50-8		0.318	mg	17885	1047
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.004	mg	225	13
				supplier	metallisation	Tantalum(Ta)	7440-25-7		0.060	mg	3375	198
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.007	mg	394	23
				supplier	metallisation	Tungsten(W)	7440-33-7		0.014	mg	787	46
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.095	mg	5343	313
				supplier	passivation	Silicon Oxide	7631-86-9		0.749	mg	42126	2466
				supplier	glass	Aluminium Oxide	1344-28-1		0.004	mg	225	13
				supplier	polymer coating	Polymer resist (color, planar,µlens)	proprietary		0.088	mg	4949	290
				supplier	CORE (Mitsubishi HLB32NS)	Thermosetting resin (including filler)	proprietary		46.080	mg	356381	151739
				supplier	CORE (Mitsubishi HLB32NS)	Fiber Glass wool	65997-17-3		24.458	mg	189157	80539
				Substrate	M-015 Other organic materials	129.300	mg	supplier	CORE (Mitsubishi HLB32NS)	Copper(Cu)	7440-50-8	
supplier	solder mask (TAIYO PSR-4000 AUS320)	Acrylic resin	9003-01-4						11.059	mg	85529	36416
supplier	solder mask (TAIYO PSR-4000 AUS320)	Barium sulfate	7727-43-7						1.536	mg	11879	5058
supplier	solder mask (TAIYO PSR-4000 AUS320)	Silica vitreous	7631-86-9						1.536	mg	11879	5058
supplier	solder mask (TAIYO PSR-4000 AUS320)	Talc	14807-96-6						0.768	mg	5940	2529
supplier	solder mask (TAIYO PSR-4000 AUS320)	Additive	proprietary						0.461	mg	3564	1517
supplier	prepeg MITSUBISHI GHPL-830NS (SN71)	Fiber glass	65997-17-3						5.471	mg	42310	18015
supplier	prepeg MITSUBISHI GHPL-830NS (SN71)	Thermosetting resin	25722-66-1						3.433	mg	26549	11304
supplier	prepeg MITSUBISHI GHPL-830NS (SN71)	Amorphous silica	7631-86-9						0.989	mg	7651	3258
supplier	Copper	Copper	7440-50-8						19.706	mg	152402	64889
supplier	Copper	Zinc	7440-66-6						0.010	mg	76	32
supplier	Copper	Chromium	7440-47-3						0.002	mg	15	6
California 65	Copper	Nickel	7440-02-0						0.005	mg	37	16
supplier	Copper	Copper	7440-50-8						12.074	mg	93380	39759
supplier	Gold	Gold	7440-57-5						0.168	mg	1300	554
California 65	Nickel	Nickel	7440-02-0						1.191	mg	9210	3921
Die attach (2053S)	M-015 Other organic materials	4.600	mg					supplier	Epoxy	Bisphenol A epoxy diacrylate	55818-57-0	
				supplier	Epoxy	Neopentyl glycol dimethacrylate	1985-51-9		0.690	mg	150000	2272
				supplier	Epoxy	Phenoxyethyl acrylate	48145-04-6		0.690	mg	150000	2272
				supplier	Epoxy	Bis F epoxy resin	28064-14-4		0.184	mg	4000	606
				supplier	Epoxy	Epoxyde bisphenol A resin	25068-38-6		0.046	mg	10000	151
				supplier	Epoxy	Acrylonitrile butadiene glycidol co-polymer	163440-98-0		0.138	mg	30000	454
				supplier	Epoxy	1,4-bis[(2,3-epoxypropoxy)methyl]cyclohexane	14228-73-0		0.138	mg	30000	454
				supplier	Epoxy	Fluorinated compound	proprietary		0.018	mg	4000	61
				supplier	Epoxy	resin	proprietary		2.006	mg	436000	6604
Glass Epoxy (BS3770)	M-015 Other organic materials	5.200	mg	supplier	Adhesive (cured)	Polyurethane	proprietary		2.860	mg	550000	9418
				supplier	Adhesive (cured)	white mineral oil	8042-47-5		0.910	mg	175000	2997
				supplier	Adhesive (cured)	Silica, vitreous	60676-86-0		0.780	mg	150000	2568
				supplier	Adhesive (cured)	Silica, amorphous	67762-90-7		0.260	mg	50000	856
				supplier	Adhesive (cured)	Titanium dioxide	13463-67-7		0.026	mg	5000	86
				supplier	Adhesive (cured)	Additives	proprietary		0.364	mg	70000	1199
Bonding wire	M-008 Precious metals	0.900	mg	supplier	wire	Gold	7440-57-5		0.891	mg	990000	2934
				supplier	wire	Other	Proprietary		0.009	mg	10000	30
Mold compound (G760S)	M-015 Other organic materials	25.400	mg	supplier	mold compound	Epoxy resin	85954-11-6		1.778	mg	70000	5855
				supplier	mold compound	Silica(Amorphous) A	60676-86-0		19.050	mg	750000	62731
				supplier	mold compound	Silica(Amorphous) B	7631-86-9		3.810	mg	150000	12546
				supplier	mold compound	Aluminum Hydroxide	21645-51-2		0.635	mg	25000	2091
Solder balls	Solder	37.600	mg	supplier	mold compound	Carbon black	1333-86-4		0.127	mg	5000	418
				supplier	solder alloy	Tin(Sn)	7440-31-5		36.284	mg	965000	119481
				supplier	solder alloy	Silver(Ag)	7440-22-4		1.128	mg	30000	3714
				supplier	solder alloy	Copper(Cu)	7440-50-8		0.188	mg	5000	619
Glass		82.900	mg	supplier	Optical glass	SILICON DIOXIDE	7631-86-9		54.012	mg	651530	177859
				supplier	Optical glass	ALUMINIUM OXIDE	1344-28-1		2.474	mg	29841	8146
				SVHC	Optical glass	BORON TRIOXIDE	1303-86-2		6.597	mg	79576	21723
supplier	Optical glass	SODIUM OXIDE	1313-59-3		6.597	mg	79576	21723				



			supplier	Optical glass	POTASSIUM OXIDE	12136-45-7		5.772	mg	69629	19008
			supplier	Optical glass	ZINC OXIDE	1314-13-2		4.123	mg	49735	13577



			supplier	Optical glass	TITANIUM DIOXIDE	13463-67-7		2.474	mg	29841	8146
			0	Optical glass	SELENIUM DIOXIDE	7446-08-4		0.412	mg	4974	1358
			supplier	SiO2	Quartz (SiO2)	14808-60-7		0.209	mg	2521	688
			supplier	Ti3O5	Titanium oxide (Ti3O5)	12065-65-5		0.230	mg	2777	758